

IN THE SPECIFICATION:

Please Amend the paragraph beginning on page 1, line 9 in accordance with the following mark-up:

The present application is a continuation-in-part of the following co-pending U.S. Patent applications: "IMPRINTED INTEGRATED CIRCUIT SUBSTRATE AND METHOD FOR IMPRINTING AN INTEGRATED CIRCUIT SUBSTRATE" Serial number 09/884,193 filed June 19<sup>th</sup>, 2001, and issued as U.S. Patent 6,967,124 on November 22, 2005; "INTEGRATED CIRCUIT SUBSTRATE HAVING LASER-EMBEDDED CONDUCTIVE PATTERNS AND METHOD THEREFOR", serial number 10/138,225 filed May 1, 2002 and issued as U.S. Patent 6,930,256 on August 16, 2005; "SOLDERABLE INJECTION-MOLDED INTEGRATED CIRCUIT SUBSTRATE AND METHOD THEREFOR" serial number 09/931,144, filed August 16, 2001 and issued as U.S. Patent 6,784,376 on August 31, 2004; and "INTEGRATED CIRCUIT FILM SUBSTRATE HAVING EMBEDDED CONDUCTIVE PATTERNS AND VIAS", serial number 10/261,868 filed October 1, 2002. Each of the above-listed parent applications has at least one common inventor and is assigned to the same assignee. The specifications of all of the above-listed parent applications are incorporated herein by reference.

Please Amend the paragraph beginning on page 13, line 3 in accordance with the following mark-up:

Referring now to Figures 4A-4C, alternative land designs for circular lands are depicted, such as lands suitable for solderball attach. Land 28A1 is a circular land formed from multiple circular regions 33A disposed radially about a larger central circular region 33B. The regions are connected by conductive channels 32B so that all of the regions are electrically connected. Land 28A1 provides a reduction in dimpling due to a current density reduction, while maintaining a larger central area than land 28B ~~grid-28A~~ of Figure 3A, which provides a greater mechanical attachment strength and may be preferable for external solderball terminal attachment points. Similarly, Land 28A2 is a circular land formed from multiple annular segments 33D disposed circumferentially at a common radius about a larger central circular region 33C. The regions are connected by conductive channels 32C so that all of the regions are electrically connected. Land 28A2 is an alternative to land 28A1 having similar properties of dimpling reduction while retaining a larger central area. Finally, Figure 4C depicts another circular land 28A3 that includes a circular central area 33E and a single annulus 33F disposed around central area 33F and connected by conductive channels 32D. Land 28A3 is another alternative to land 28A1 having similar properties of dimpling

reduction while retaining a larger central area.

Please Amend the paragraph beginning on page 14, line 13 in accordance with the following mark-up:

Referring now to Figure 5B, another integrated circuit 50B is shown exemplifying a wire bonded configuration. Die 52B 26B is mounted to substrate 10D ~~10C~~ with an adhesive (generally epoxy) and wires 58 are bonded between plated lands formed in substrate 10D. A SMT component 53 is attached to lands 28B having a grid pattern as described above and as shown in a top view of the circuit area in balloon 55. Solder balls 56 are added to the external terminal locations. Substrate 10D is manufactured according to the same steps as substrate 10C of Figure 5A, but has different circuit patterns, lands and die mounting area for accommodating wire-attach type die 52B.